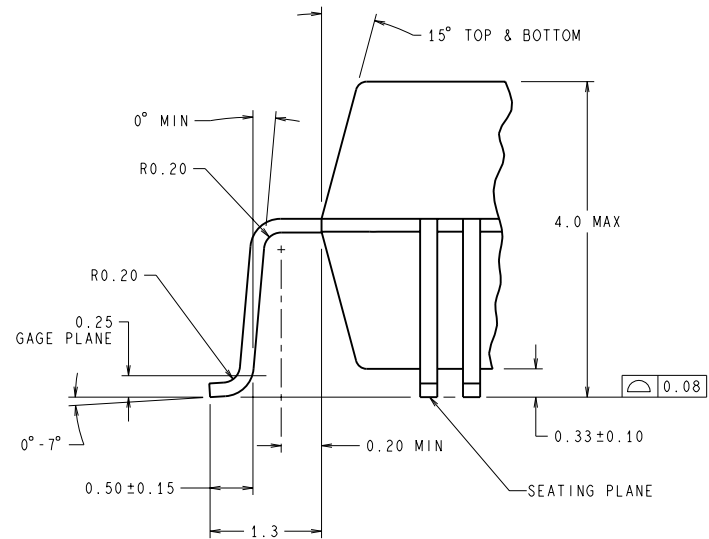
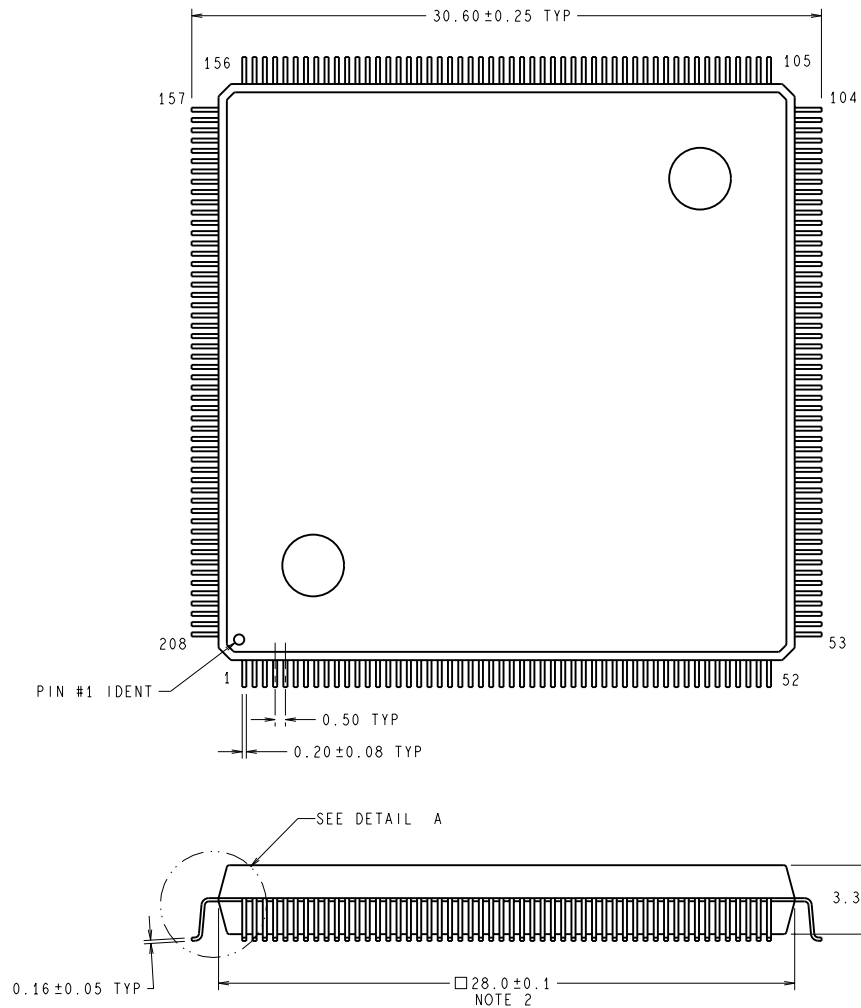


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	09735	05/04/93	DEG/HJK
B	REV DATE ON NOTE 3 & TOLERANCES; ADD 15° ANGLE; REDRAW ON PRO/E	10897	03/20/95	TL/



DETAIL A
TYP. SCALE: 25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE SEIKO EPSON QFP8-208 PIN S1, REV 1.0,
DATED 8/02/94.

APPROVALS		DATE	National Semiconductor		
DRAWN	T. LEUANG	03/20/95	2900 Semiconductor dr. Santa Clara, CA 95052-8090		
DFTG. CHK.			PQFP, (S), 28 X 28 X 3.4mm, 208 LEAD		
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VUF208A	B
INCH MM		DO NOT SCALE DRAWING		SHEET 1 of 1	